

FAQ

Q1: What is the next-generation AMD notebook platform?

A1: On June 4, 2008, AMD announced its next-generation notebook platform which is comprised of the following components:

- AMD Turion™ X2 Ultra Dual-Core Mobile Processors
- AMD 7-Series chipset for notebooks including the AMD M780G chipset with ATI Radeon HD 3200 integrated graphics, the AMD M780V chipset with ATI Radeon 3100 integrated graphics, the M780 with ATI Mobility Radeon HD 3000 Series discrete graphics, and the AMD SB700 Southbridge.
- ATI Mobility Radeon™ HD 3000 Series Graphics including the previously announced ATI Mobility Radeon™ 3400 and 3600, and the new ATI Mobility Radeon™ 3800, delivering the highest levels of graphics performance in the ATI Mobility Radeon HD family.
- The latest Draft 802.11n and 3G wireless technologies from industry leaders.

Q2: Why is this launch important to AMD?

A2: While the desire for mobility is clearly driving notebook sales, how those notebooks are being used is changing too, and until now most users have been woefully disappointed by the visual experience. Notebook PCs based on the next-generation AMD platform are designed to deliver the ultimate in HD visual performance on the go. Additionally, we are seeing an increase in the attach rate of discrete graphics due to the demand by consumers and business professionals for the ultimate visual experience with Microsoft Windows Vista.

With this next-generation AMD notebook platform, AMD has nearly doubled the number of design wins over the last major technology announcement which was the introduction of dual-core into the AMD Turion 64 family. As well, the number of AMD notebooks with discrete graphics has increased by approximately 30 percent over the last major technology introduction of dual-core into the AMD Turion™ family.

Q3: What are AMD Turion™ X2 Ultra processors?

A3: AMD Turion X2 Ultra is a new brand extension under the AMD Turion brand for notebook processors, previously codenamed "Griffin." AMD Turion X2 Ultra processors are designed to deliver a higher level of performance for the ultimate in HD visual performance on the go.

Q4: What is ATI Hybrid CrossFireX™?

A4: Based on ATI CrossFireX™ multi-GPU technology, ATI Hybrid CrossFireX™ enables a cost effective way to boost 3D graphics performance up to 1.7X by combining an ATI Mobility Radeon HD 3400 Series discrete graphics controller with the ATI Radeon HD 3200 integrated graphics. Additionally, ATI CrossFireX brings multi-monitor functionality to the mainstream notebook.

Q5: Which OEMs plan to offer systems with this next-generation AMD notebook platform?

A5: AMD customers have overwhelmingly accepted this new platform, as evidenced by nearly two times the number of design wins over the last major technology introduction of AMD Turion™ technology. These new notebook designs come from leading OEMs including Acer, Asus, Fujitsu, FSC, HP, MSI, NEC and Toshiba.

Q6: Do ATI Mobility Radeon HD 3000 Series Graphics deliver greater performance as part of the next-generation AMD notebook platform, compared to a similar configuration with an Intel processor?

A6: ATI Mobility Radeon HD 3000 series graphics when combined with the AMD Turion X2 Ultra processors and the AMD 7-Series chipset will offer exceptional visual performance and power-efficiency gains, to enhance the user experience. As AMD is able to offer the processor, chipset and graphics, we expect to be able to offer capabilities that are not possible when using technologies that don't have a unified set of software drivers. As well, when AMD notebooks are streaming video using our partner's Draft 802.11n wireless, we will offer a superior experience.

Q7: What is the Better by Design program?

A7: Delivering the best PC platforms to the marketplace is the goal of the Better by Design program. While mobility and entertainment are still top of the list, the advent of Windows Vista OS is moving the world toward a new level of computing experience – one with increased emphasis on graphics capabilities and mobility – and notebook PC users are not willing to compromise. Simply put, they want notebook PCs that are better by design and AMD helps make that a reality.

AMD and its technology partners like Atheros, Broadcom, Marvell, Nvidia, Ralink and others are working together to deliver platforms based on superior technologies to OEMs and enabling a better notebook PC experience for PC users around the world. Notebook PC buyers should look for the unique Better by Design label to know that they have a system that enables the better visual experience they expect from Windows Vista and other graphics-intensive applications.

Q8: What kind of performance do you expect from the next-generation AMD notebook platform?

A8: Our goal for this next generation AMD notebook platform is to deliver the ultimate in HD visual performance. This requires a balanced platform, and not just a good CPU. Depending upon how the consumer or business professional configures the notebook and what applications they run, they will realize different levels of performance. In comparing the visual experience of the next generation AMD notebook platform to the only platform in the market from our competitor, we deliver up to 5x the 3D graphics performance for much more responsive game play, Microsoft DirectX10 for a much more realistic and immersive 3D visual experience as compared to DX9 offered on Centrino, up to 5x the HD image quality for a sharper picture as measured by HQV, and nearly 40% faster wireless transfer of HD content with Draft 802.11n for a more responsive experience while connected to the internet on the go.

Q9: How did AMD chipset designers contribute to the next-generation AMD notebook platform?

A9: The next-generation AMD notebook platform demonstrates the compounding value to customers of AMD's CPU and chipset capabilities. The development effort involved microprocessor and chipset engineers working to bring increased energy efficiency, battery life and performance to end-users. With the next-generation AMD notebook platform, we have attained a significant level of coordination in how the chipset and CPU communicate in such areas as power efficiency and HT3 connectivity.

